

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC057N03LS G	**Issued**	29. August 2013
MA#	MA001118218		
Package	PG-TDSON-8-14	**Weight***	118.84 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.076	0.91	0.91	9058	9058
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		82	
	non noble metal	zinc	7440-66-6	0.039	0.03		327	
	non noble metal	iron	7439-89-6	0.778	0.65		6547	
	non noble metal	copper	7440-50-8	31.590	26.58	27.27	265821	272777
wire	non noble metal	copper	7440-50-8	0.058	0.05	0.05	485	485
encapsulation	organic material	carbon black	1333-86-4	0.240	0.20		2018	
	plastics	epoxy resin	-	7.435	6.26		62560	
	inorganic material	silicondioxide	60676-86-0	40.291	33.91	40.37	339037	403615
leadfinish	non noble metal	tin	7440-31-5	1.243	1.05	1.05	10456	10456
plating	noble metal	silver	7440-22-4	0.037	0.03	0.03	315	315
solder	non noble metal	tin	7440-31-5	0.026	0.02		220	
	noble metal	silver	7440-22-4	0.033	0.03		275	
	non noble metal	lead	7439-92-1	1.250	1.05	1.10	10517	11012
heatspreader	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	zinc	7440-66-6	0.021	0.02		180	
	non noble metal	iron	7439-89-6	0.428	0.36		3598	
	non noble metal	copper	7440-50-8	17.360	14.61	14.99	146079	149902
heat sink CLIP	non noble metal	iron	7439-89-6	0.017	0.01		142	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		43	
	non noble metal	copper	7440-50-8	16.898	14.22	14.23	142195	142380
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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